Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	"4057659".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:33
L2	0	remove near metal near edge near laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:33
L3	24	remove near metal near laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:33
L4	6	3 and edge	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:45
L5	2348	219/121.69	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:46
L6	820	427/555	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:46
L8	284	427/556	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:46
 L9 	3102	5 or 6 or 8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:46
L10	2846	9 and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:47

L11	1840	10 and metal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:47
L12	48	11 and metal near remove	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:47
S1	2573	via near etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 09:29
S2	2296989	angle or angled	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:45
S3	335381	via and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:45
S4	3048512	via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:45
S5	3660	S2 near S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:46
S6	64	first near via near etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:46
S7	23	second near via near etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:47
S8	519107	taper or tapered	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR ·	ON	2006/06/07 13:46

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S9 	2016	S8 near S4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:56
S11	231310	"193"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:50
S12	57	S9 and S11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:53
S13	21	S12 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:21
S14	420	S9 and semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/07 13:59
S17	45	("4814041").URPN.	USPAT	OR	ON	2006/06/07 15:24
S18	1	"5354386".pn.	USPAT	OR	ON	2006/06/07 15:36
S19	49441	multi-layer	USPAT	OR	ON	2006/06/07 15:37
S20	834	tapered near via	USPAT	OR	ON	2006/06/07 15:42
S22	5	S19 same S20	USPAT	OR	ON	2006/06/07 15:37
S25	5	two near step near via near etch	USPAT	OR	ON	2006/06/07 15:47
S26	435	wine near glass	USPAT	OR	ON	2006/06/07 16:26
S27	130	S26 and via	USPAT	OR	ON	2006/06/07 15:47
S28	39	S27 and semiconductor	USPAT	OR	ON	2006/06/07 16:10
S29	16206	ARC and dielectric	USPAT	OR	ON	2006/06/07 16:10
S30	5	S28 and S29	USPAT	OR	ON	2006/06/07 16:21
S31	115	ARC near resist	USPAT	OR	ON	2006/06/07 16:21
S33	0	ARC near "193" near nm near resist	USPAT	OR	ON	2006/06/07 16:21
S34	158	"193" near nm near resist	USPAT	OR	ON	2006/06/07 16:21
S35	34	S34 and arc	USPAT	OR	ON	2006/06/07 16:22
S36	18	S35 and via	USPAT	OR	ON	2006/06/07 16:22
S37	5	wine near glass near via	USPAT	OR	ON	2006/06/07 16:28
S38	38	fluted near via	USPAT	OR	ON	2006/06/08 11:58

S50 1 "6743712".pn. USPAT OR ON 2006/06 S51 2195 SLAM USPAT OR ON 2006/06 S52 263 SLAM and ARC USPAT OR ON 2006/06 S53 26 S52 and taper USPAT OR ON 2006/06 S54 5 S53 and semiconductor USPAT OR ON 2006/06 S55 13 S52 and semiconductor USPAT OR ON 2006/06 S56 2198 tapered near sidewall USPAT OR ON 2006/06 S57 177 S56 and arc USPAT OR ON 2006/06 S58 69 S57 and via USPAT OR ON 2006/06 S59 29 S58 and semiconductor USPAT OR ON 2006/06 S61 25 S56 and reflective USPAT OR ON 2006/06 S62 1	/07 16:28 /07 16:37 /07 16:37 /07 16:37 /07 16:38 /07 16:38 /07 16:40 /07 17:01 /07 16:55
S51	/07 16:37 /07 16:37 /07 16:38 /07 16:38 /07 16:40 /07 17:01
S52 263 SLAM and ARC USPAT OR ON 2006/06 S53 26 S52 and taper USPAT OR ON 2006/06 S54 5 S53 and semiconductor USPAT OR ON 2006/06 S55 13 S52 and semiconductor USPAT OR ON 2006/06 S56 2198 tapered near sidewall USPAT OR ON 2006/06 S57 177 S56 and arc USPAT OR ON 2006/06 S58 69 S57 and via USPAT OR ON 2006/06 S59 29 S58 and semiconductor USPAT OR ON 2006/06 S60 104 S56 and reflective USPAT OR ON 2006/06 S61 25 S56 and antireflective USPAT OR ON 2006/06 S62 1 "6368959",pn. USPAT OR ON 2006/06 S64	/07 16:37 /07 16:38 /07 16:38 /07 16:40 /07 17:01
S53 26 S52 and taper USPAT OR ON 2006/06 S54 5 S53 and semiconductor USPAT OR ON 2006/06 S55 13 S52 and semiconductor USPAT OR ON 2006/06 S56 2198 tapered near sidewall USPAT OR ON 2006/06 S57 177 S56 and arc USPAT OR ON 2006/06 S58 69 S57 and via USPAT OR ON 2006/06 S59 29 S58 and semiconductor USPAT OR ON 2006/06 S60 104 S56 and reflective USPAT OR ON 2006/06 S61 25 S56 and antireflective USPAT OR ON 2006/06 S62 1 "6368959".pn. USPAT OR ON 2006/06 S63 1 "4814041".pn. USPAT OR ON 2006/06 S64	/07 16:38 /07 16:38 /07 16:40 /07 17:01
S54 5 S53 and semiconductor USPAT OR ON 2006/06 S55 13 S52 and semiconductor USPAT OR ON 2006/06 S56 2198 tapered near sidewall USPAT OR ON 2006/06 S57 177 S56 and arc USPAT OR ON 2006/06 S58 69 S57 and via USPAT OR ON 2006/06 S59 29 S58 and semiconductor USPAT OR ON 2006/06 S60 104 S56 and reflective USPAT OR ON 2006/06 S61 25 S56 and antireflective USPAT OR ON 2006/06 S62 1 "6368959".pn. USPAT OR ON 2006/06 S63 1 "4814041".pn. USPAT OR ON 2006/06 S64 103 silicon near arc USPAT OR ON 2006/06 S65 <td>/07 16:38 /07 16:40 /07 17:01</td>	/07 16:38 /07 16:40 /07 17:01
S55 13 S52 and semiconductor USPAT OR ON 2006/06 S56 2198 tapered near sidewall USPAT OR ON 2006/06 S57 177 S56 and arc USPAT OR ON 2006/06 S58 69 S57 and via USPAT OR ON 2006/06 S59 29 S58 and semiconductor USPAT OR ON 2006/06 S60 104 S56 and reflective USPAT OR ON 2006/06 S61 25 S56 and antireflective USPAT OR ON 2006/06 S62 1 "6368959".pn. USPAT OR ON 2006/06 S63 1 "4814041".pn. USPAT OR ON 2006/06 S64 103 silicon near arc USPAT OR ON 2006/06 S65 206 organic near arc USPAT OR ON 2006/06	/07 16:40 /07 17:01
S56 2198 tapered near sidewall USPAT OR ON 2006/06 S57 177 S56 and arc USPAT OR ON 2006/06 S58 69 S57 and via USPAT OR ON 2006/06 S59 29 S58 and semiconductor USPAT OR ON 2006/06 S60 104 S56 and reflective USPAT OR ON 2006/06 S61 25 S56 and antireflective USPAT OR ON 2006/06 S62 1 "6368959".pn. USPAT OR ON 2006/06 S63 1 "4814041".pn. USPAT OR ON 2006/06 S64 103 silicon near arc USPAT OR ON 2006/06 S65 206 organic near arc USPAT OR ON 2006/06	/07 17:01
S57 177 S56 and arc USPAT OR ON 2006/06 S58 69 S57 and via USPAT OR ON 2006/06 S59 29 S58 and semiconductor USPAT OR ON 2006/06 S60 104 S56 and reflective USPAT OR ON 2006/06 S61 25 S56 and antireflective USPAT OR ON 2006/06 S62 1 "6368959".pn. USPAT OR ON 2006/06 S63 1 "4814041".pn. USPAT OR ON 2006/06 S64 103 silicon near arc USPAT OR ON 2006/06 S65 206 organic near arc USPAT OR ON 2006/06	
S58 69 S57 and via USPAT OR ON 2006/06 S59 29 S58 and semiconductor USPAT OR ON 2006/06 S60 104 S56 and reflective USPAT OR ON 2006/06 S61 25 S56 and antireflective USPAT OR ON 2006/06 S62 1 "6368959".pn. USPAT OR ON 2006/06 S63 1 "4814041".pn. USPAT OR ON 2006/06 S64 103 silicon near arc USPAT OR ON 2006/06 S65 206 organic near arc USPAT OR ON 2006/06	/07 16:55
S59 29 S58 and semiconductor USPAT OR ON 2006/06 S60 104 S56 and reflective USPAT OR ON 2006/06 S61 25 S56 and antireflective USPAT OR ON 2006/06 S62 1 "6368959".pn. USPAT OR ON 2006/06 S63 1 "4814041".pn. USPAT OR ON 2006/06 S64 103 silicon near arc USPAT OR ON 2006/06 S65 206 organic near arc USPAT OR ON 2006/06	
S60 104 S56 and reflective USPAT OR ON 2006/06 S61 25 S56 and antireflective USPAT OR ON 2006/06 S62 1 "6368959".pn. USPAT OR ON 2006/06 S63 1 "4814041".pn. USPAT OR ON 2006/06 S64 103 silicon near arc USPAT OR ON 2006/06 S65 206 organic near arc USPAT OR ON 2006/06	/07 16:55
S61 25 S56 and antireflective USPAT OR ON 2006/06 S62 1 "6368959".pn. USPAT OR ON 2006/06 S63 1 "4814041".pn. USPAT OR ON 2006/06 S64 103 silicon near arc USPAT OR ON 2006/06 S65 206 organic near arc USPAT OR ON 2006/06	/07 16:56
S62 1 "6368959".pn. USPAT OR ON 2006/06 S63 1 "4814041".pn. USPAT OR ON 2006/06 S64 103 silicon near arc USPAT OR ON 2006/06 S65 206 organic near arc USPAT OR ON 2006/06	/07 17:01
S63 1 "4814041".pn. USPAT OR ON 2006/06 S64 103 silicon near arc USPAT OR ON 2006/06 S65 206 organic near arc USPAT OR ON 2006/06	/08 08:28
S64 103 silicon near arc USPAT OR ON 2006/06 S65 206 organic near arc USPAT OR ON 2006/06	/08 08:29
S65 206 organic near arc USPAT OR ON 2006/06	/08 08:34
	/08 08:34
S66 294 S64 or S65 USPAT OR ON 2006/06	/08 08:34
	/08 08:34
S67 49073 international adj business USPAT OR ON 2006/06	/08 08:35
S68 45767 international adj business adj USPAT OR ON 2006/06 machines.as.	/08 08:35
S69 1 15 S66 and S68 USPAT OR ON 2006/06	/08 08:44
S70 2719 (taper or tapered) near sidewall USPAT OR ON 2006/06	/08 08:44
S71 11 tunable adj arc USPAT OR ON 2006/06	/08 08:44
S72 1 S70 and S65 USPAT OR ON 2006/06	/08 08:46
S74 138 tapered adj via USPAT OR ON 2006/06	/08 08:53
S75 9195 PSG USPAT OR ON 2006/06	/08 08:53
S76 15715 TEOS USPAT OR ON 2006/06	/08 08:53
S77 222344 ARC USPAT OR ON 2006/06	/08 08:53
S78 252742 resist or photoresist or ("193" adj USPAT OR ON 2006/06 nm)	6/08 08:53
S79 155 S75 and S76 and S77 and S78 . USPAT OR ON 2006/06	6/08 11:51
S80 1245177 "38" and "34" USPAT OR ON 2006/06	6/08 11:59
S81 158 "193" near nm near resist USPAT OR ON 2006/06	5/08 11:58
S82 38 fluted near via USPAT OR ON 2006/06	100 11.50
S83 0 S82 and S81 USPAT OR ON 2006/06	0,00 11:50
S84 834 tapered near via USPAT OR ON 2006/00	5/08 11:58

S85	112	"193" near resist	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 11:59
S86	1528	tapered near via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:01
S87	331	sloped near via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:00
S88	1	angeled near via ′	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:00
S91	2	"193" same S86	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:02
S92	2580	via near etch	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:02
S93	1	"193" same S92	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:36
S94 	1528	tapered near via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:20
S95	1665254	semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:21
 S96 	345	S94 and S95	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:24

S97	127	S96 and via.ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:24
S98 	1	"60437080"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/08 12:36
S99		"6874510".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 10:45
S10 0	1	10/829392	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 13:02
S10 1	2	"5875896".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 10:07
S10 2	. 2	"6683277".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 10:07
S10 3	52	resist adj spin adj coat	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 10:45
S10 4	1	resist adj spin adj coat.ti.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/11 10:45